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PATENT
Atty. Dkt. No. APPM/005975.P2/MDP/L/B/CROCKER S

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Ganguli et al.

Serial No.: 10/811,230

Confirmation No.: 8995

Filed: March 26, 2004

For: Ruthenium Layer Formation
for Copper Film Deposition

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Group Art Unit: 1792

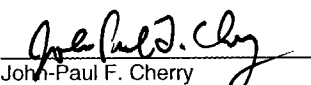
Examiner: Kelly M. Stouffer

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Kelly M. Stouffer, on the date shown below.

July 8, 2008
Date


John-Paul F. Cherry

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED APRIL 8, 2008

In response to the Final Office Action dated April 8, 2008, having a shortened statutory period for response set to expire on July 8, 2008, please enter this Response and reconsider the claims pending in the application for reasons discussed below. Although the Applicant believes that no additional fees are due in connection with this Response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005975.P2/JPC, for any fees, including extension of time fees or excess claim fees, required to make this Response timely and acceptable to the Office.

Pending Claims begin on page 2 of this paper. **Remarks** begin on page 13 of this paper.